

REFERENCE NUMERALS AND SYMBOLS AS SHOWN IN THE DRAWINGS

1 Chuck; 2 Semiconductor substrate; 3 Resist material;
4 Arm; 5 Receiving portion; 6 Filter.

Specification

Table I. Sequence of Embodiment

Step	Time (sec)	Rotational velocity (rpm)	Depositing of resist
1	1.0	1500	-
2	0.8	0	O
3	1.0	3700	O
4	0.4	800	O
5	1.0	800	-
6	20.0	2940	-

Table II. Sequence of Comparative Example

Step	Time (sec)	Rotational velocity (rpm)	Depositing of resist
1	1.0	1500	-
2	4.0	1500	O

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3	1.0	800	-
4	20.0	2940	-

Table III. Sequence of Embodiment 2.

Step	Time (sec)	Rotational velocity (rpm)	Depositing of resist
1	20.0	1000	-
2	0.3	0	O
3	0.4	3000	O
4	0.3	1500	O
5	0.3	1000	-
6	25.0	2010	-

Table IV. Sequence of Comparative Example 2.

Step	Time (sec)	Rotational velocity (rpm)	Depositing of resist
1	1.0	1000	-
2	2.5	1000	O
3	0.3	1000	-
4	25.0	2030	-

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Table V. Sequence of Embodiment 3.

Step	Time (sec)	Rotational velocity (rpm)	Depositing of resist
1	20.0	700	-
2	0.2	0	O
3	0.3	3000	O
4	0.2	1500	O
5	4.0	1500	-
6	3.0	4610	-
7	19.0	4610	-

Table VI. Sequence of Comparative Example 3.

Step	Time (sec)	Rotational velocity (rpm)	Depositing of resist
1	2.0	700	-
2	6.0	1500	O
3	0.5	1500	-
4	3.0	4800	-
5	19.0	4800	-

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